

2026 EUVL and Source Workshop

June 6 - 7, 2026 (Online Only Short Courses)

June 8 - 11, 2026 (Held In-Person only at Pauley Ballroom, UC Berkeley)



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2026 EUVL and Source Workshop

Workshop Photographs

Workshop Chair: Vivek Bakshi (EUV Litho)

Workshop Co-Chairs: Patrick Naulleau (EUV Tech), Ricardo Ruiz (Molecular Foundry/LBL),
Michael Bartl (UC Berkeley), and Oscar Versolato (ARCNL)

Local Host and Program Organizers: UC Berkeley

EUVL and Source Workshop Group Photograph



Blue-X TWG Group Photograph



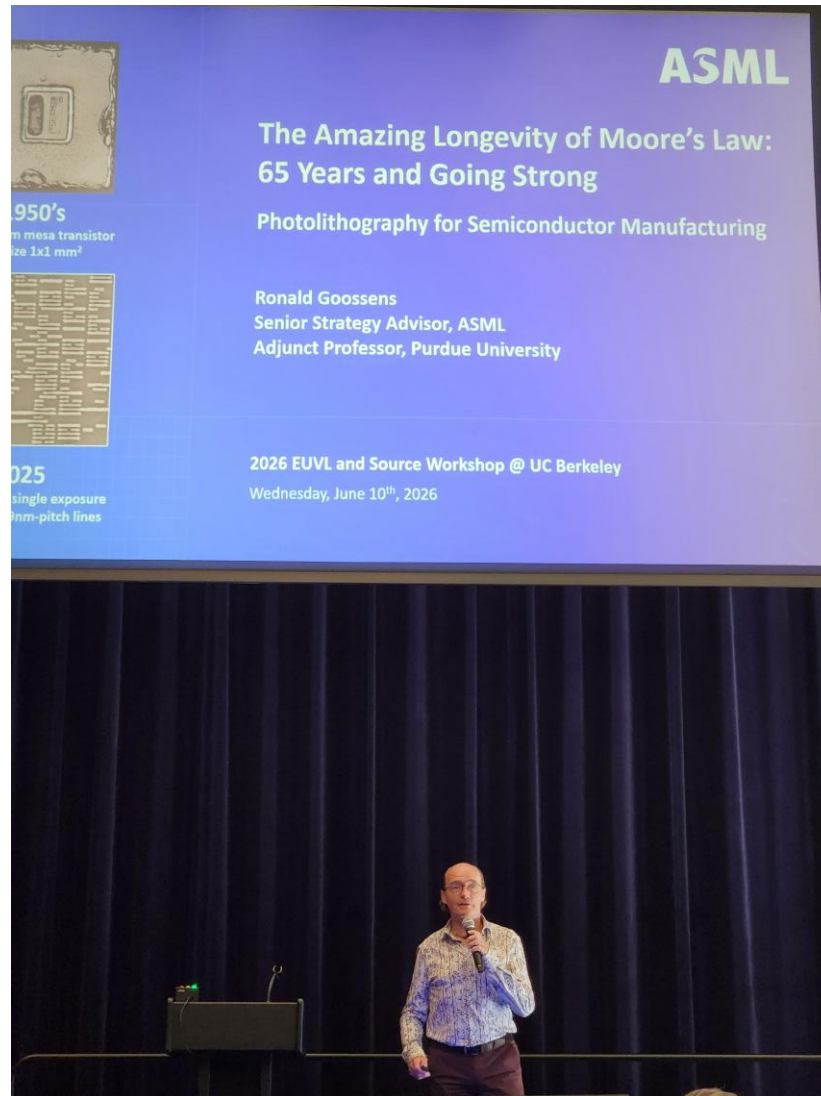
The Venue



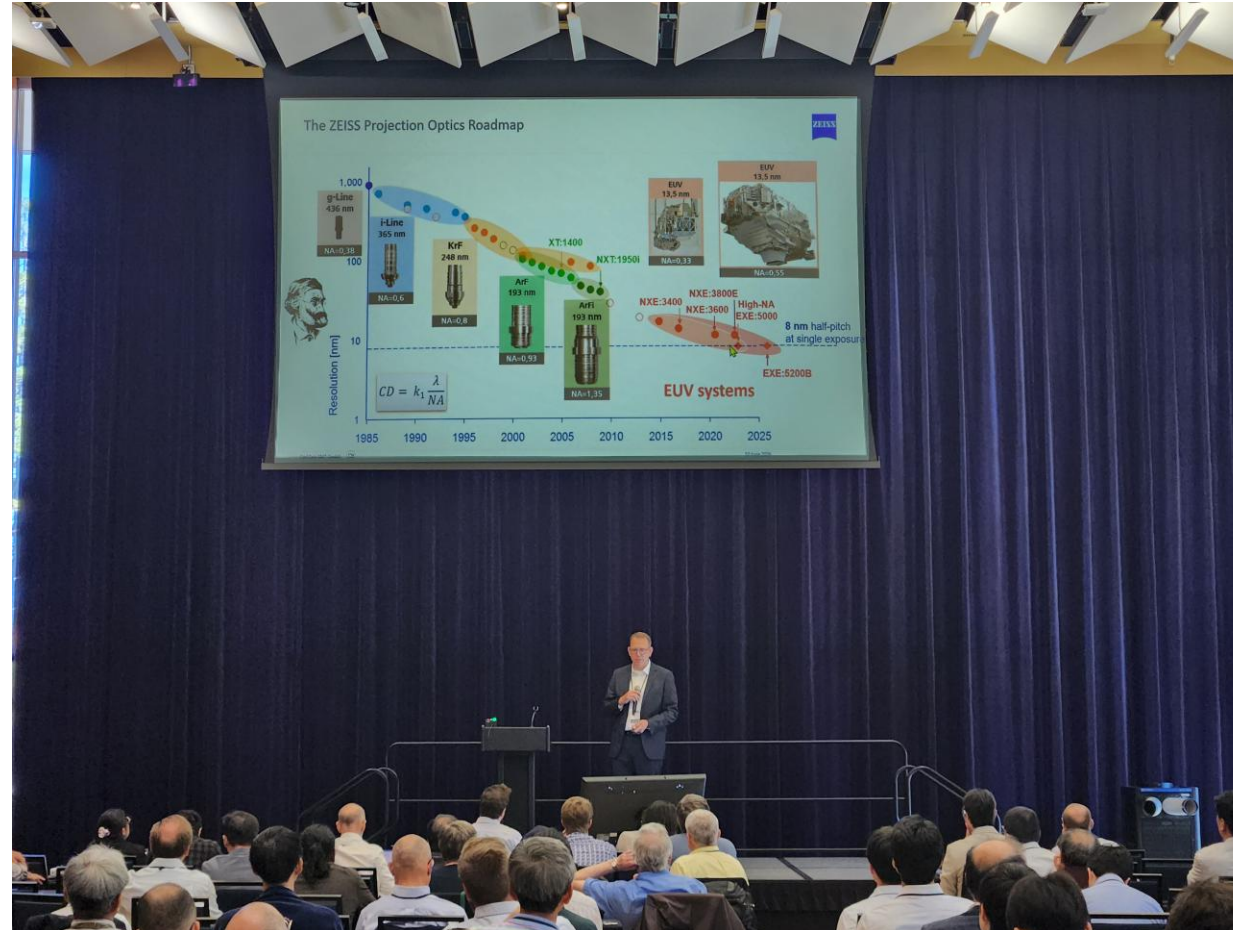
The Audience



Technical Sessions



Technical Sessions



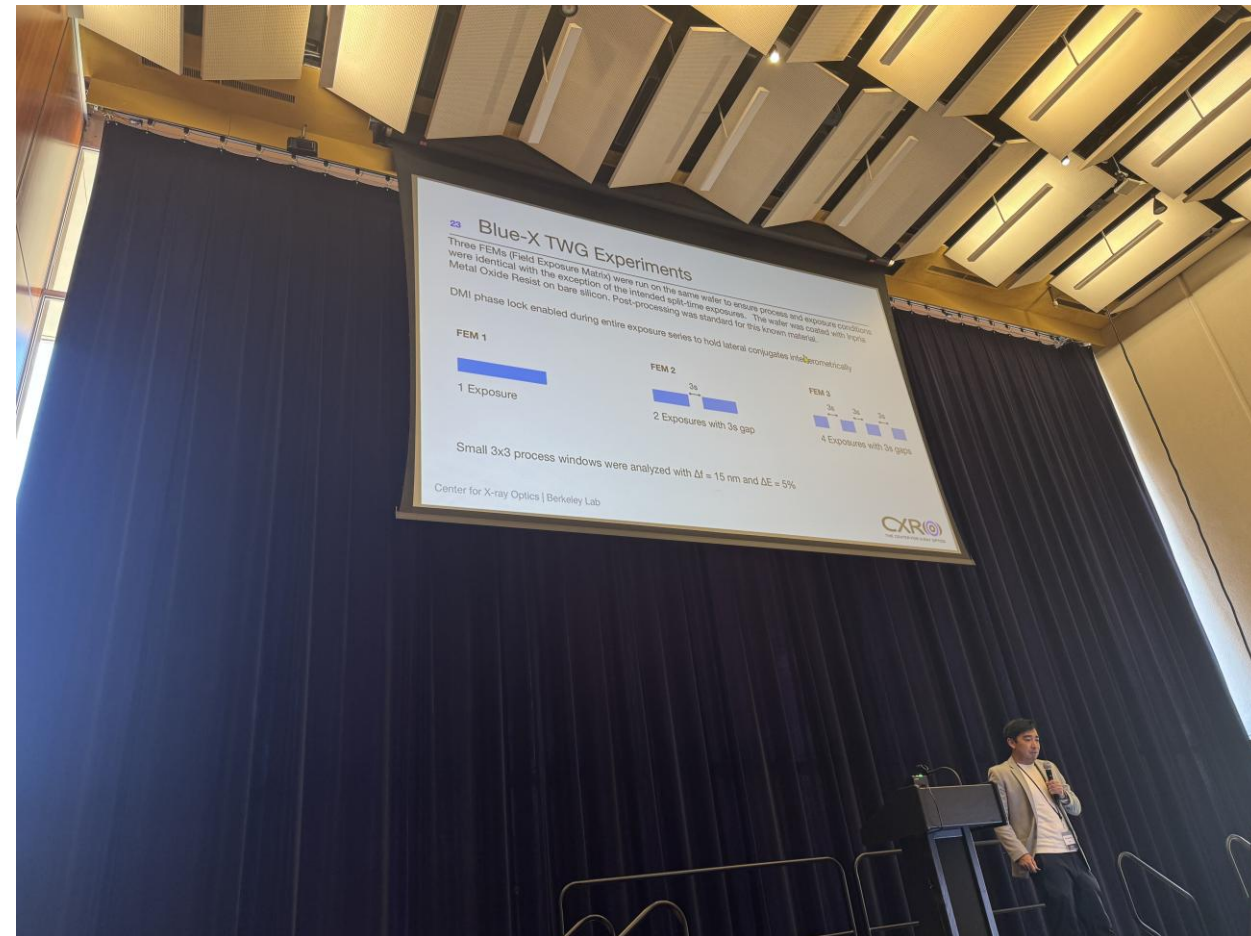
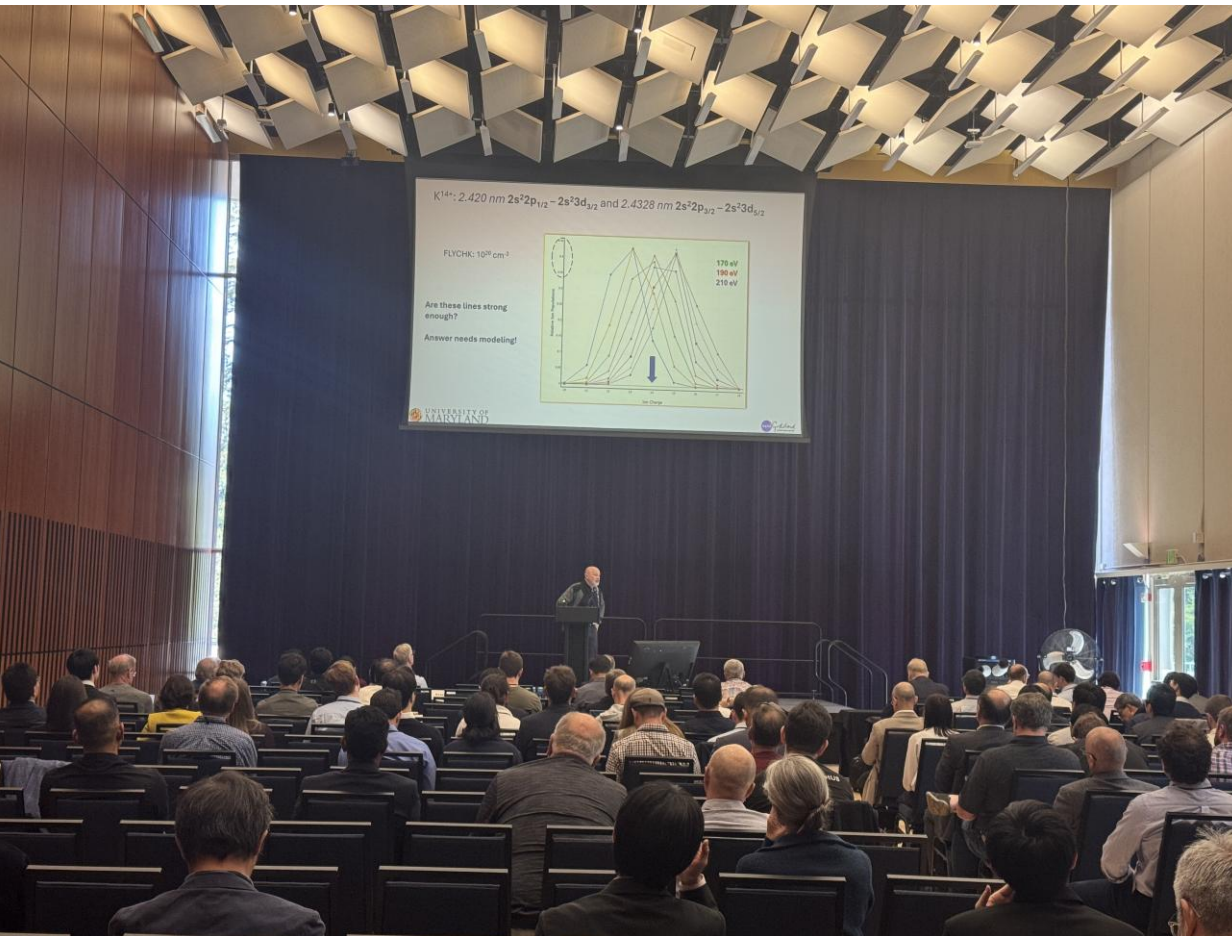
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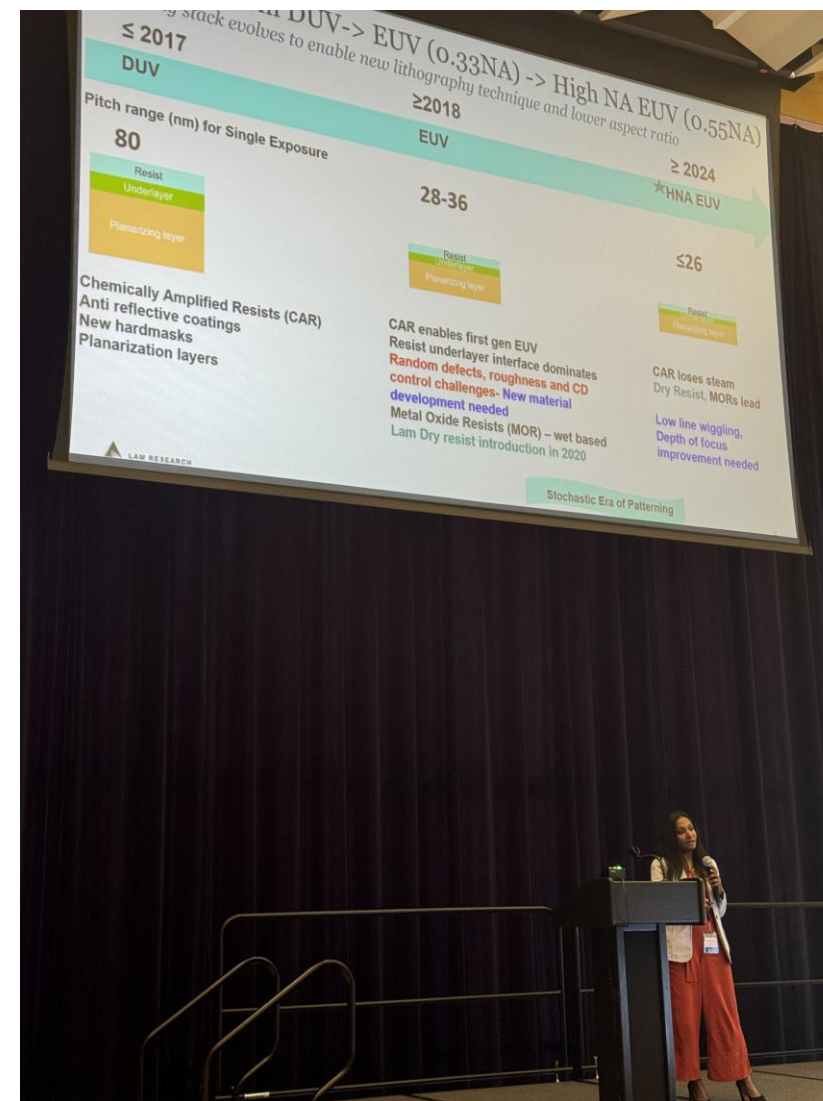
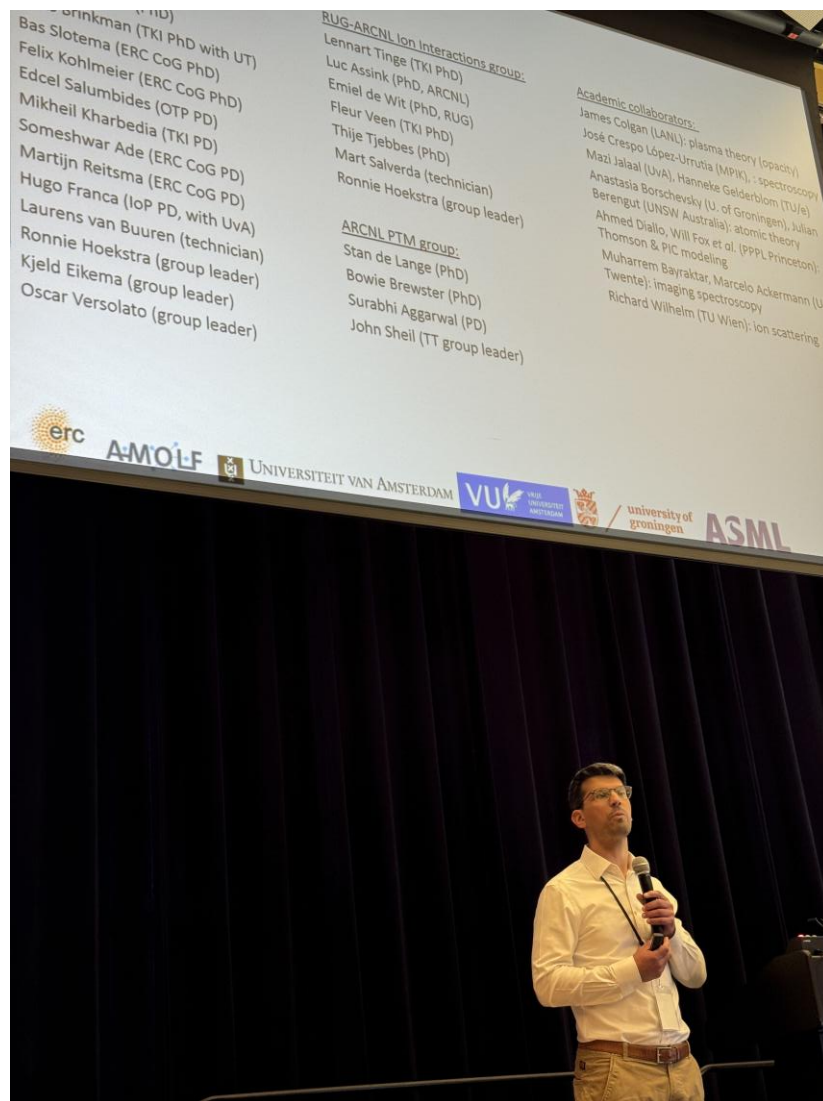
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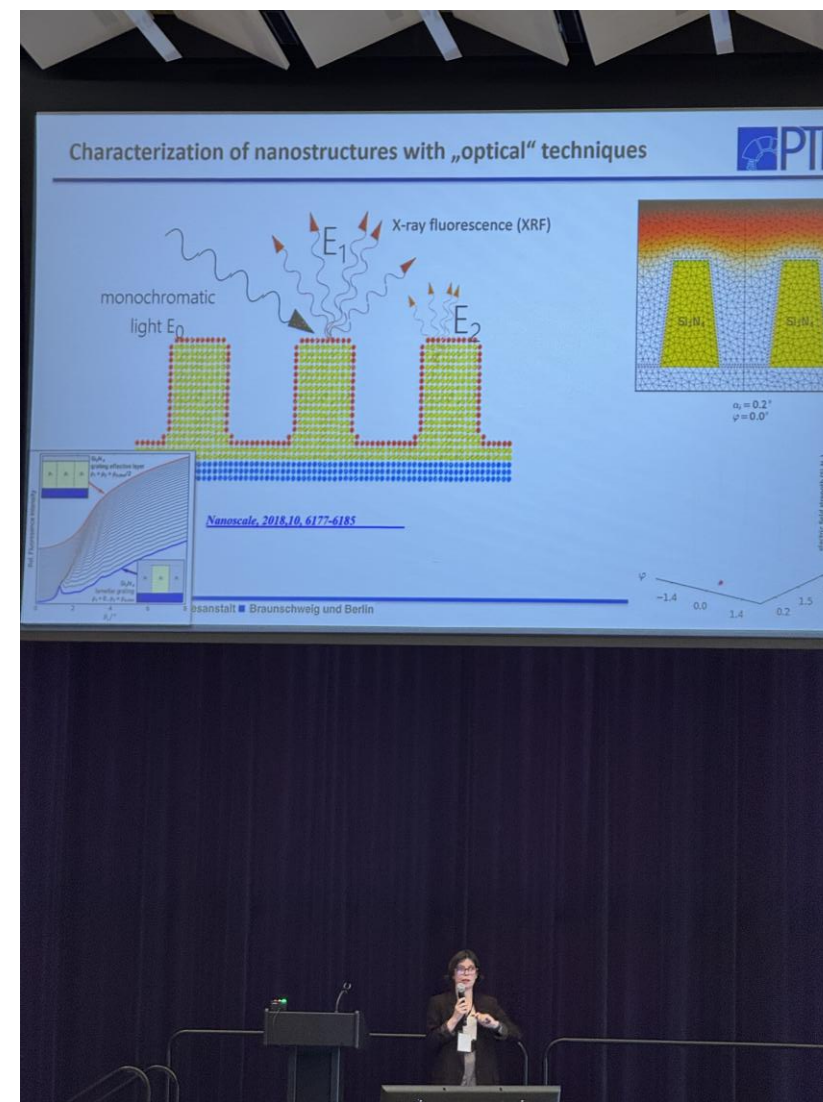
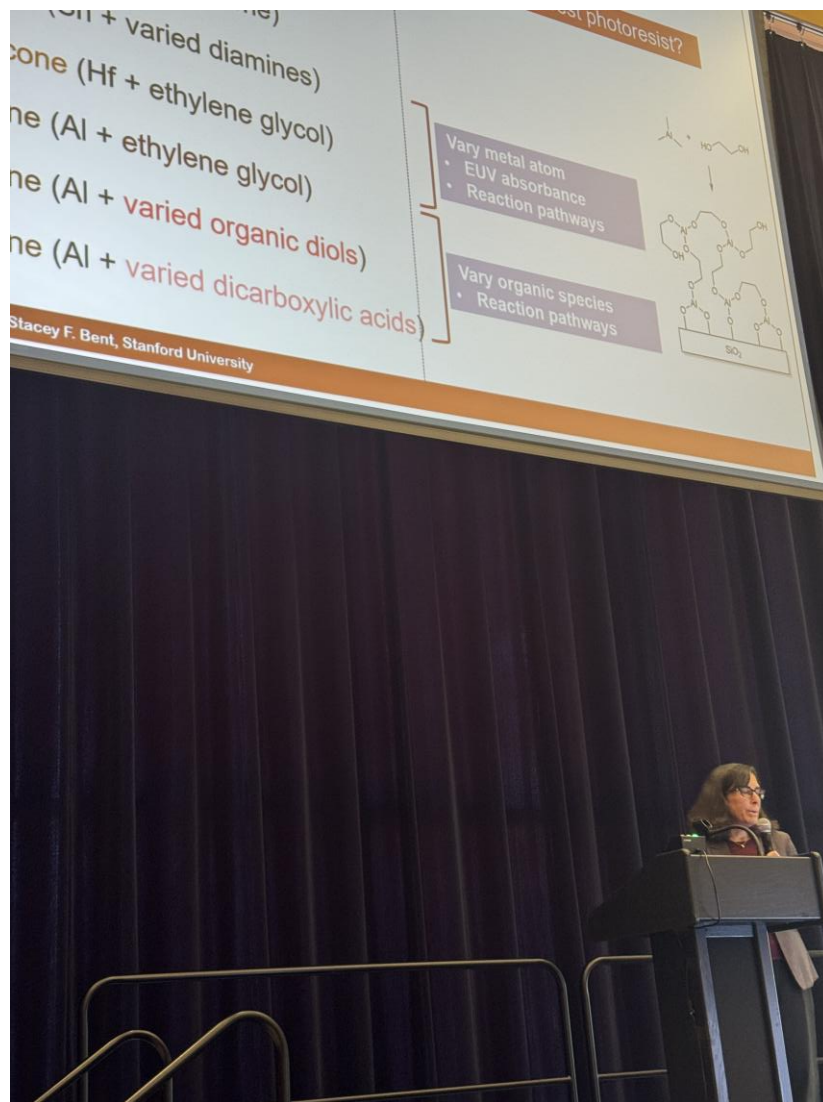
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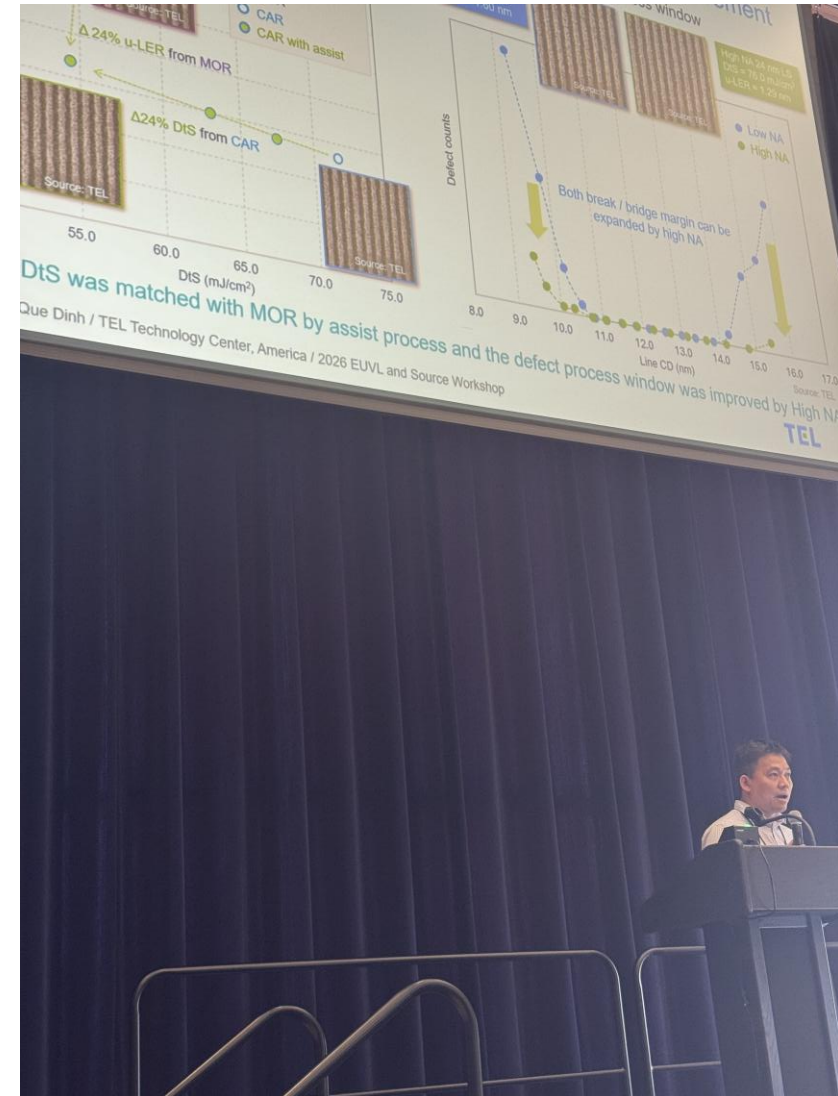
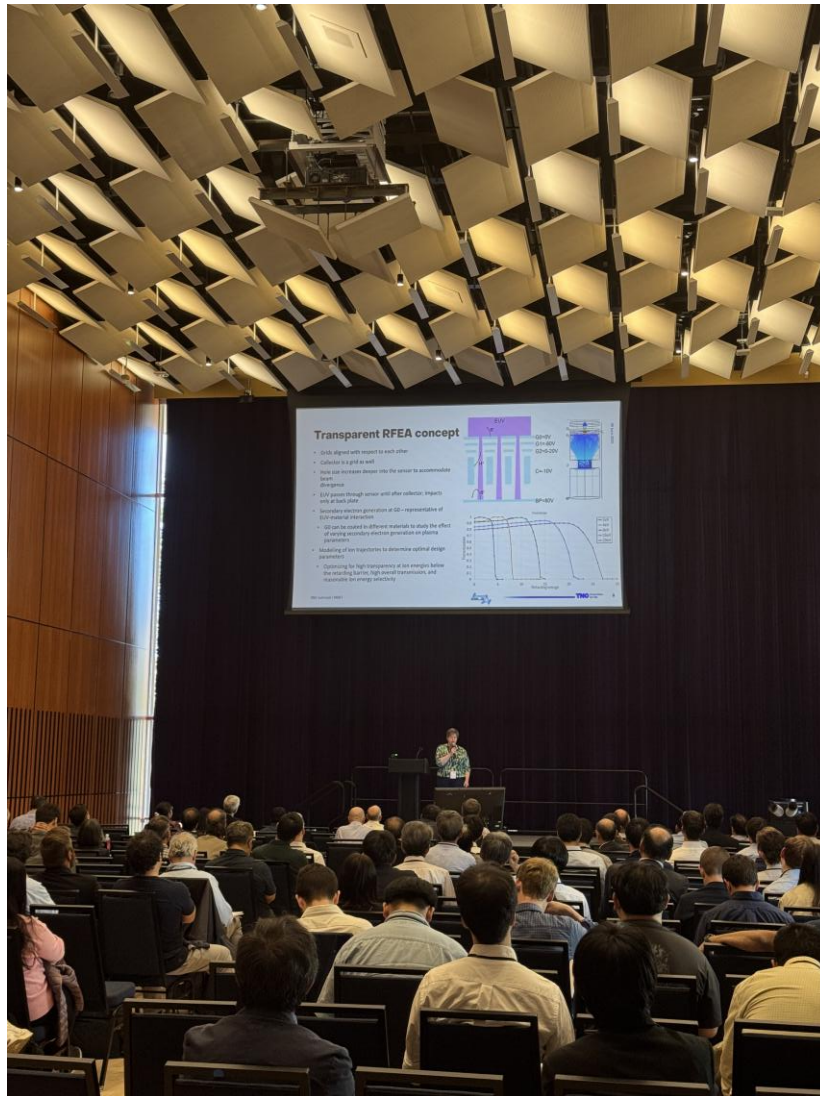
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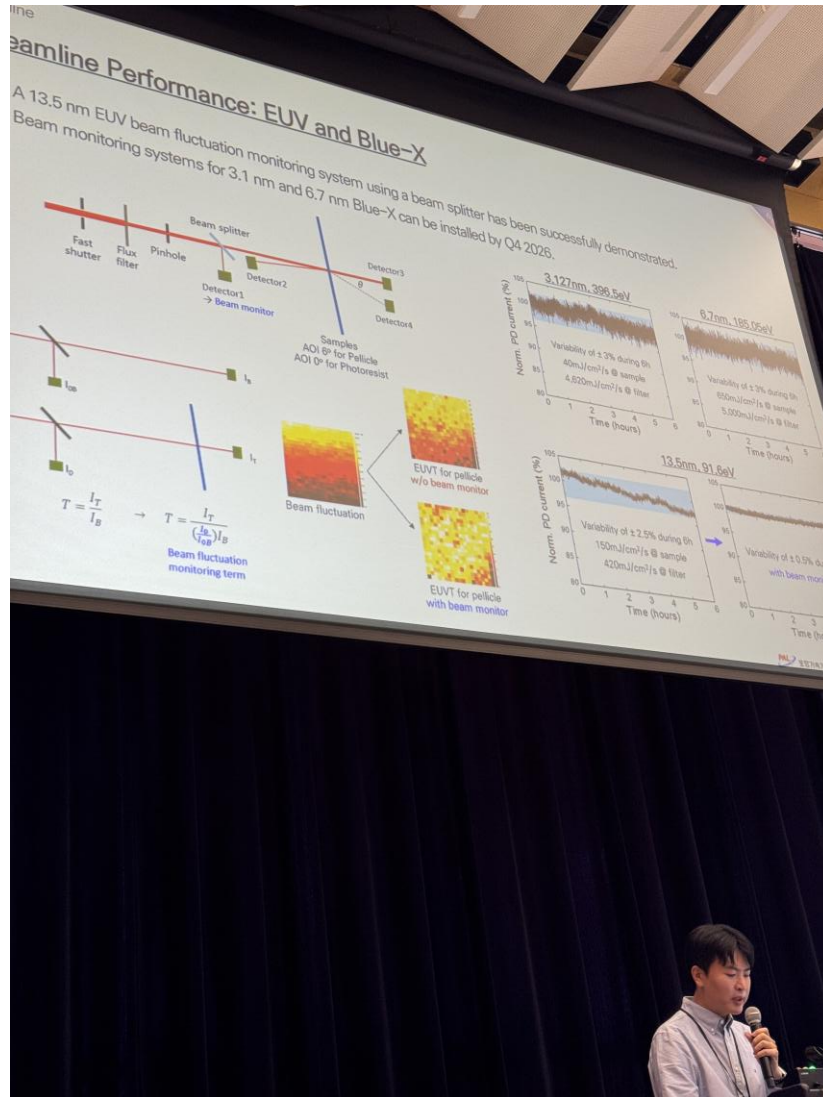
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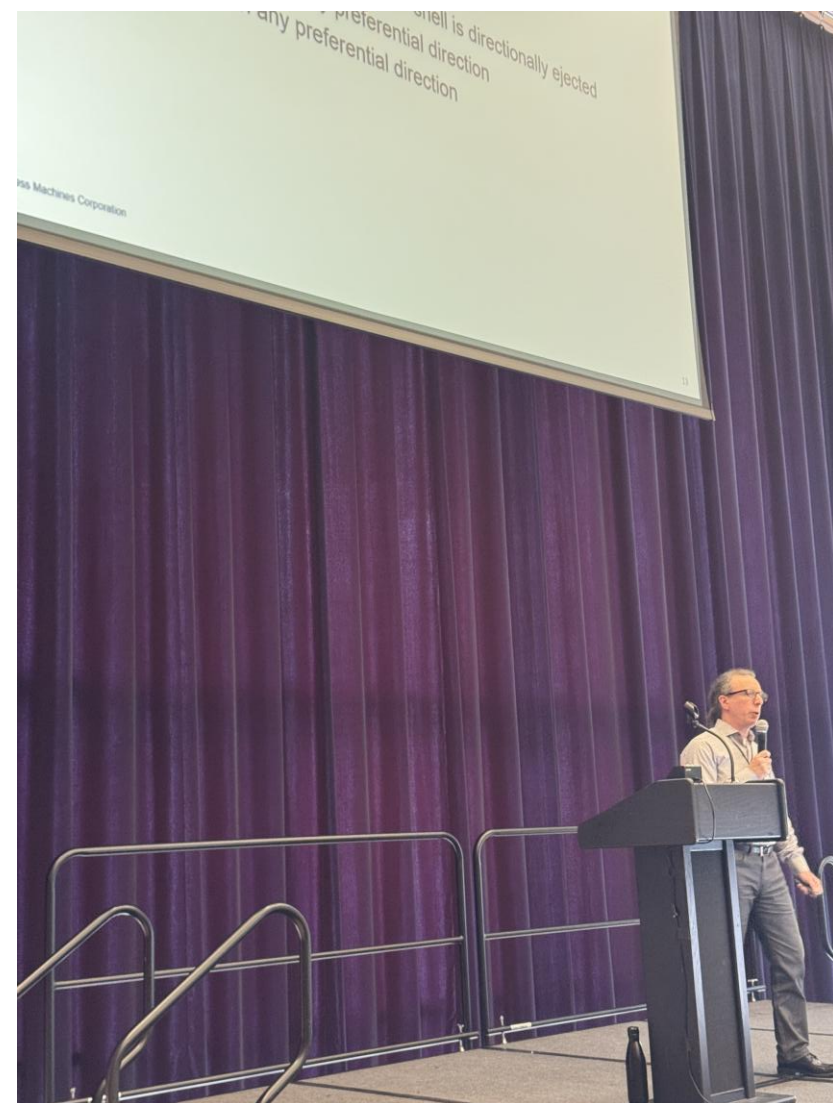
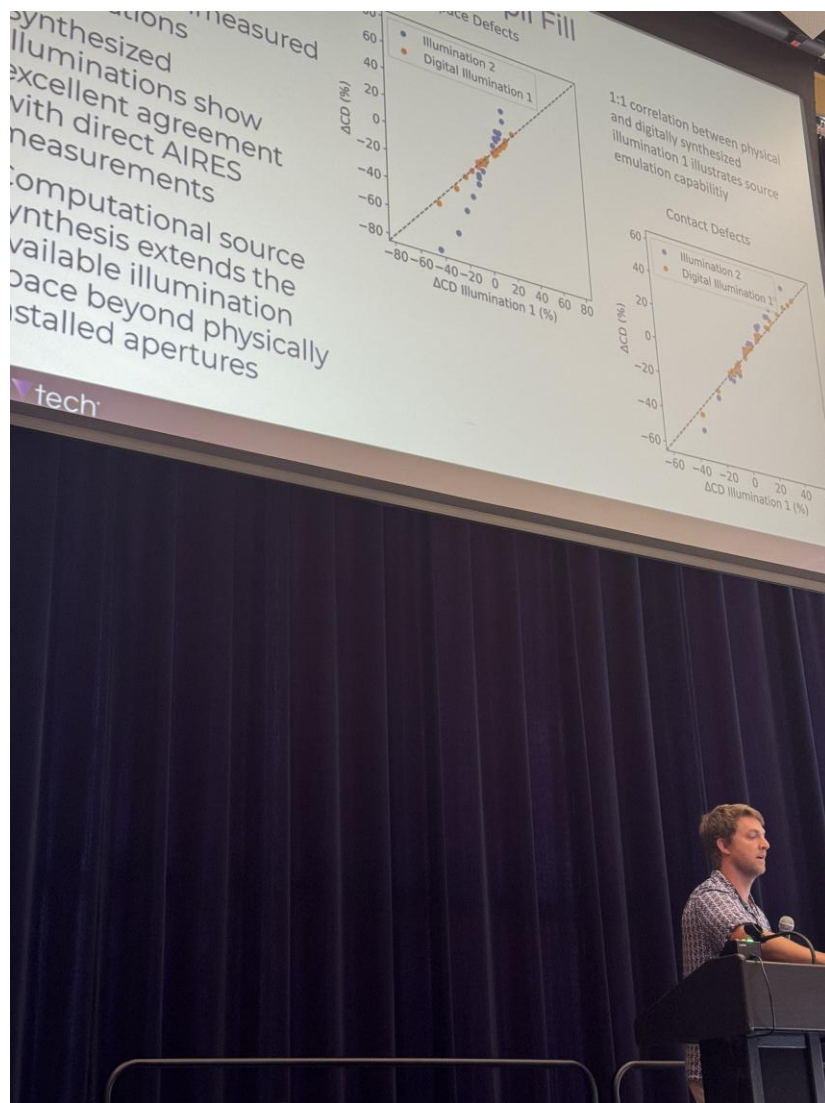
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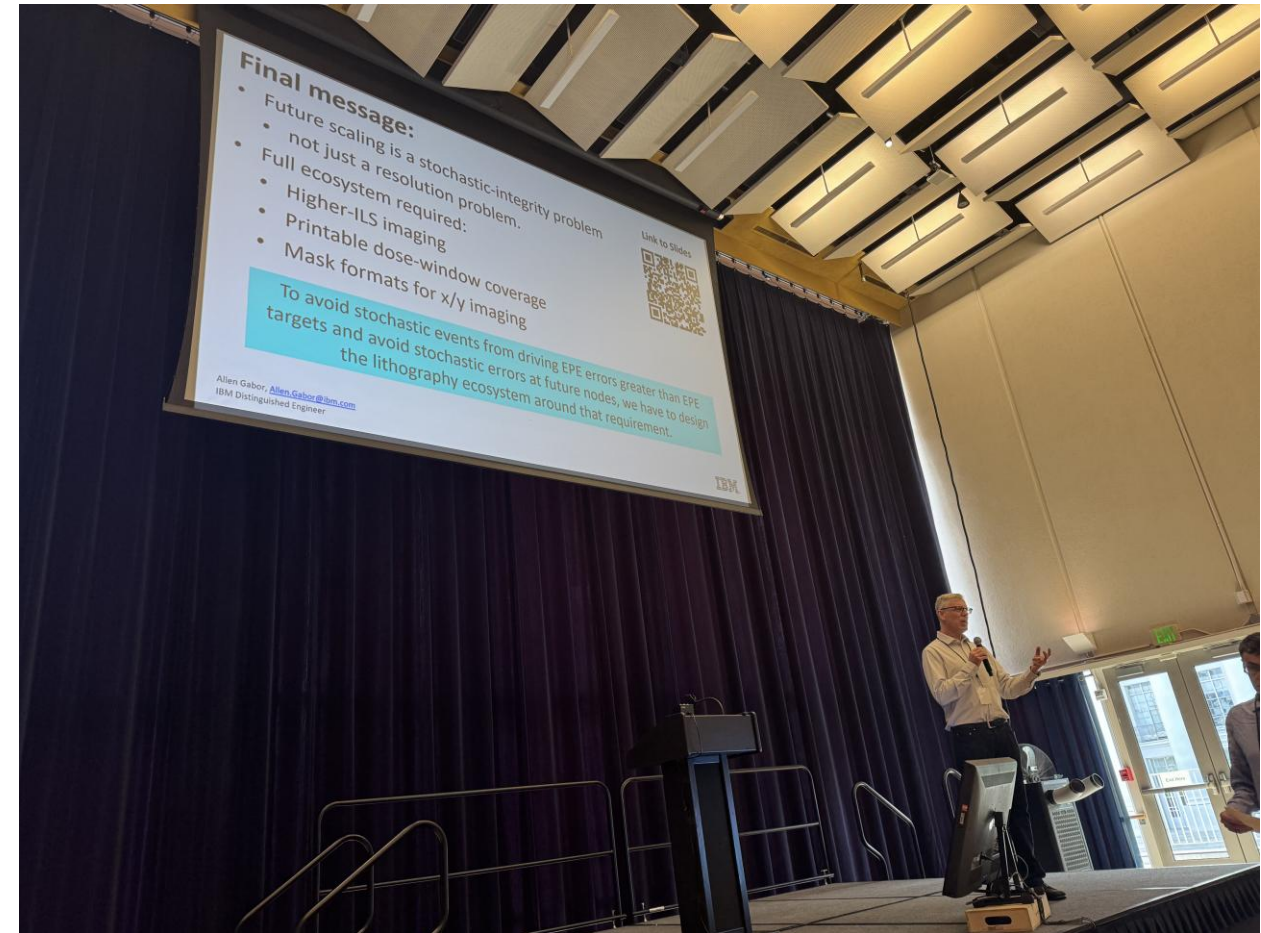
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Technical Sessions

Transparent RFEA concept

- Grids aligned with respect to each other
- Collector is a grid as well
- Hole size increases deeper into the sensor to accommodate beam divergence
- EUV passes through sensor until after collector; impacts only at back plate
- Secondary electron generation at G0 – representative of EUV-material interaction
- G0 can be coated in different materials to study the effect of varying secondary electron generation on plasma parameters
- Modelling of ion trajectories to determine optimal design parameters
- Optimizing for high transparency at ion energies below the retarding barrier, high overall transmission, and reasonable ion energy selectivity

Final design

Experimental data

TNO restricted | DRIAT

TNO International for Life

System Architecture

reliability and stability for HVM → Predictive smart process etc.

control → In-situ metrology

egrated process flow to build the entire mirror

lights out manufacturing

with AI capabilities

Requirement Challenges

- Substrate CTE & thermal-mechanical requirements
- ~500 deposition layers → **Very long process time**
- Control of interfacial layers (roughness, chemical composition)
- Tighter specs on CWL uniformity and defectivity
- Large form factor Pellicle

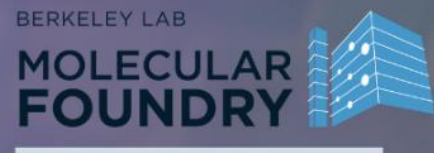
Investment Timing/Risk

- <15 years to intercept Hyper-NA → Time is running out
- Transition to larger mask from 12x6 → **Logistic and timing risk**
- Early awareness, assessment and planning with industry on HVM → alignment and resources to drive technology roadmap

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